

A T 2 5 1 2 8 B - S S H L - B

Product Family

25 = Standard SPI
Serial EEPROM

Device Density

128 = 128-Kilobit
256 = 256-Kilobit

Device Revision

Shipping Carrier Option

B = Bulk (Tubes)

T = Tape and Reel, Standard Quantity Option

E = Tape and Reel, Extended Quantity Option

Operating Voltage

L = 1.8V to 5.5V

**Device Grade or
Wafer/Die Thickness**

H or U = Industrial Temperature Range
(-40°C to +85°C)

11 = 11mil Wafer Thickness

Package Option

SS = SOIC

X = TSSOP

MA = 2.0mm x 3.0mm UDFN

C = VFBGA

WWU = Wafer Unsawn

WDT = Die in Tape and Reel